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MPxx5004, 0 to 3.92 kPa, Differential and Gauge, Integrated Pressure Sensor

Freescal's MPxx5004 series piezoresistive transducer is a state-of-the-art monolithic silicon pressure sensor designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This sensor combines a highly sensitive implanted strain gauge with advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

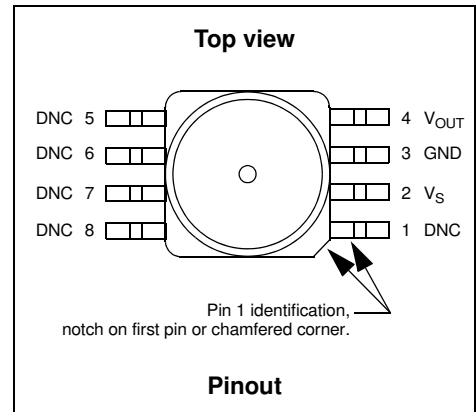
Features

- 1.5% maximum error for 0 to 100 mm H₂O over +10 °C to +60 °C with autozero
- 2.5% maximum error for 100 to 400 mm H₂O over +10 °C to +60 °C with autozero
- 6.25% maximum error for 0 to 400 mm H₂O over 10 °C to +60 °C without autozero
- Temperature compensated over 10 °C to 60 °C
- Available in gauge surface mount (SMT) or through-hole (DIP) configurations
- Durable thermoplastic (PPS) package

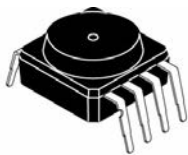
Applications

- Washing machine water level
- Ideally suited for microprocessor or microcontroller-based systems
- Appliance liquid level and pressure measurement
- Respiratory equipment

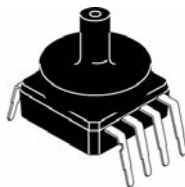
MPXV5004
MPVZ5004



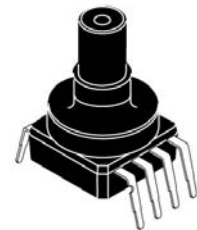
Small outline packages, through-hole



MPVZ5004G7U
Case 98ASB17758C



MPXV5004GC7U
Case 98ASB17759C

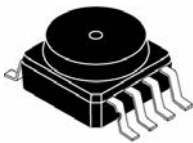


MPVZ5004GW7U
Case 98ASA10611D

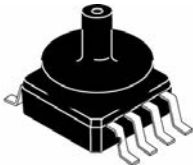
Freescal reserves the right to change the detail specifications as may be required to permit improvements in the design of its products.

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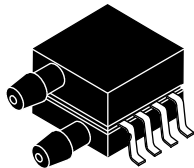
Small outline packages, surface mount



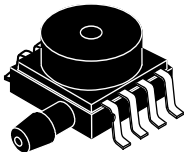
MPVZ5004G6U/6T1
Case 98ASB17756C



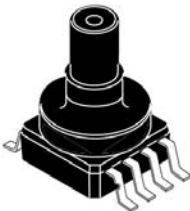
MPXV5004GC6T1/6U, MPVZ5004GC6U
Case 98ASB17757C



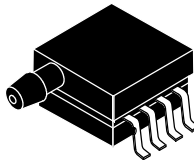
MPXV5004DP
Case 98ASA99255D



MPXV5004GVP
Case 98ASA99302D



MPVZ5004GW6U
Case 98ASA10686D



MPXV5004GP/GPT1
Case 98ASA99303D

Ordering Information									
Part number	Shipping	Package	# of Ports			Pressure type			Device marking
			None	Single	Dual	Gauge	Differential	Absolute	
Small outline package (MPXV5004 series)									
MPXV5004DP	Tray	98ASA99255D			•		•		MPXV5004DP
MPXV5004GC6T1	Reel	98ASB17757C		•		•			MPXV5004G
MPXV5004GC6U	Rail	98ASB17757C		•		•			MPXV5004G
MPXV5004GC7U	Rail	98ASB17759C		•		•			MPXV5004G
MPXV5004GP	Tray	98ASA99303D		•		•			MPXV5004GP
MPXV5004GPT1	Reel	98ASA99303D		•		•			MPXV5004GP
MPXV5004GVP	Tray	98ASA99302D		•		•			MPXV5004GVP
Small outline package (Media resistant gel) (MPVZ5004 series)									
MPVZ5004G6T1	Reel	98ASB17756C	•			•			MPVZ5004G
MPVZ5004G6U	Rail	98ASB17756C	•			•			MPVZ5004G
MPVZ5004G7U	Rail	98ASB17758C	•			•			MPVZ5004G
MPVZ5004GC6U	Rail	98ASB17757C		•		•			MPVZ5004G
MPVZ5004GW6U	Rail	98ASA10686D		•		•			MZ5004GW
MPVZ5004GW7U	Rail	98ASA10611D		•		•			MZ5004GW

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Related Documentation

The MPXV5004G device features and operations are described in a variety of reference manuals, user guides, and application notes. To find the most-current versions of these documents:

1. Go to the Freescale homepage at:
<http://www.freescale.com/>
2. In the Keyword search box at the top of the page, enter the device number MPXV5004G.
3. In the Refine Your Result pane on the left, click on the Documentation link.

1 General Description

1.1 Block diagram

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

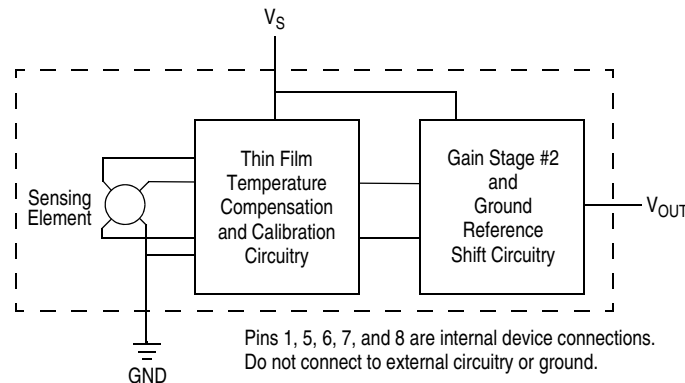


Figure 1. Integrated pressure sensor schematic

1.2 Pinout

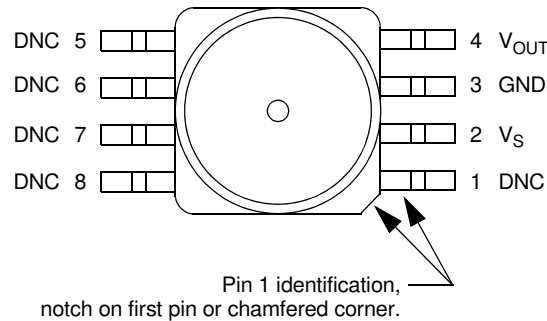


Figure 2. Device pinout (top view)

Table 1. Pin functions

Pin	Name	Function
1	DNC	Do not connect to external circuitry or ground. Pin 1 is notated by the notch in the lead or chamfered corner.
2	V_S	Voltage supply
3	GND	Ground
4	V_{OUT}	Output voltage
5	DNC	Do not connect to external circuitry or ground.
6	DNC	Do not connect to external circuitry or ground.
7	DNC	Do not connect to external circuitry or ground.
8	DNC	Do not connect to external circuitry or ground.

2 Mechanical and Electrical Specifications

2.1 Maximum ratings

Table 2. Maximum ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum pressure ($P_1 > P_2$)	P_{MAX}	16	kPa
Storage temperature	T_{STG}	-30 to +100	°C
Operating temperature	T_A	0 to +85	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

2.2 Operating characteristics

Table 3. Operating characteristics ($V_S = 5.0 V_{DC}$, $T_A = 25 ^\circ C$ unless otherwise noted, $P_1 > P_2$)

Characteristic	Symbol	Min	Typ	Max	Units
Pressure range	P_{OP}	0	—	3.92 400	kPa mm H ₂ O
Supply voltage ⁽¹⁾	V_S	4.75	5.0	5.25	V_{DC}
Supply current	I_S	—	—	10	mAdc
Span @ 306 mm H ₂ O (3 kPa) ⁽²⁾ Full-scale span @ 400 mm H ₂ O (3.92 kPa) ⁽²⁾	V_{FSS}	— —	3.0 3.92	— —	V
Offset ⁽³⁾	V_{OFF}	0.75	1.0	1.25	V
Sensitivity	V/P	—	1.0	—	V/kPa
Accuracy ⁽⁴⁾ ⁽⁵⁾ 0 to 100 mm H ₂ O (10 °C to 60 °C) 100 to 400 mm H ₂ O (10 °C to 60 °C) 0 to 400 mm H ₂ O (10 °C to 60 °C)	—	—	—	±1.5	% V_{FSS} with autozero
	—	—	—	±2.5	% V_{FSS} with autozero
	—	—	—	±6.25	% V_{FSS} without autozero

- Device is ratiometric within this specified excitation range.
- Span is defined as the algebraic difference between the output voltage at specified pressure and the output voltage at the minimum rated pressure.
- Offset (V_{OFF}) is defined as the output voltage at the minimum rated pressure.
- Accuracy (error budget) consists of the following:
 - Linearity: Output deviation from a straight line relationship with pressure, using endpoint method, over the specified pressure range.
 - Temperature hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
 - Pressure hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25 °C.
 - TcSpan: Output deviation over the temperature range of 10 °C to 60 °C, relative to 25 °C.
 - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 10 °C to 60 °C, relative to 25 °C.
 - Variation from nominal: The variation from nominal values, for offset or full-scale span, as a percent of V_{FSS} , at 25 °C.
- Autozero at factory installation: Due to the sensitivity of the MPxx5004G, external mechanical stresses and mounting position can affect the zero pressure output reading. Autozeroing is defined as storing the zero pressure output reading and subtracting this from the device's output during normal operations. Reference AN1636 for specific information. The specified accuracy assumes a maximum temperature change of ±5 °C between autozero and measurement.

3 On-chip Temperature Compensation and Calibration

The performance over temperature is achieved by integrating the shear-stress strain gauge, temperature compensation, calibration and signal conditioning circuitry onto a single monolithic chip.

Figure 3 illustrates the gauge configuration in the basic chip carrier (case 98ASB17756C). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPxx5004 series sensor operating characteristics are based on use of dry air as pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Internal reliability and qualification test for dry air, and other media, are available from the factory. Contact the factory for information regarding media tolerance in your application.

Figure 4 shows the recommended decoupling circuit for interfacing the output of the MPxx5004 to the A/D input of the microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

Typical, minimum and maximum output curves are shown for operation over a temperature range of 10 °C to 60 °C using the decoupling circuit shown in Figure 4. The output will saturate outside of the specified pressure range.

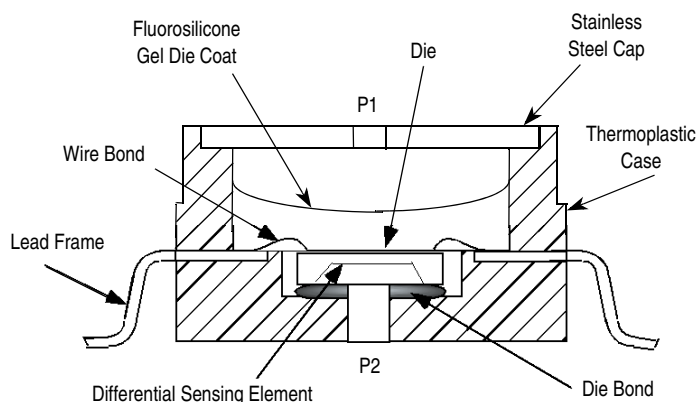


Figure 3. Cross-sectional diagram (not to scale)

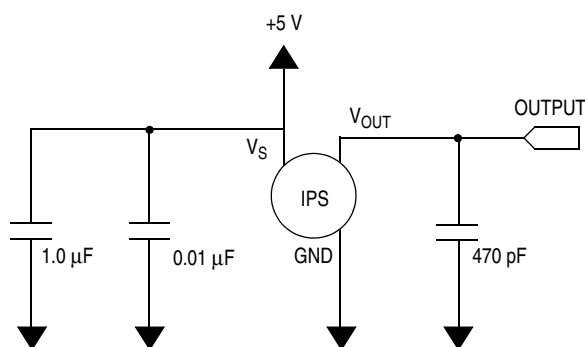


Figure 4. Recommended power supply decoupling and output filtering
(For additional output filtering, please refer to AN1646.)

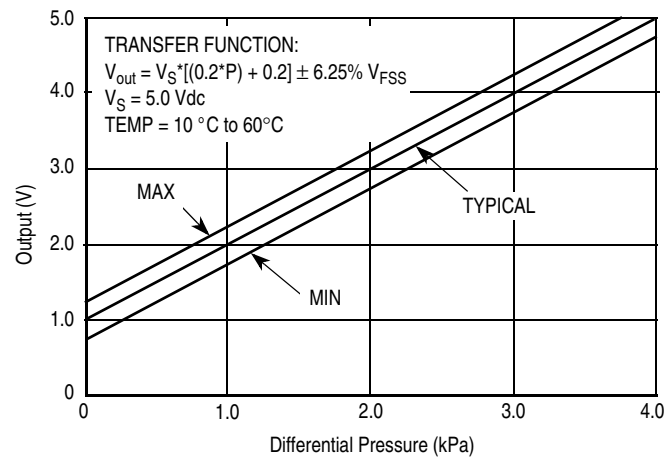


Figure 5. Output vs. pressure differential at $\pm 6.25\% V_{FSS}$ (without autozero, [Table 3](#), note 5)

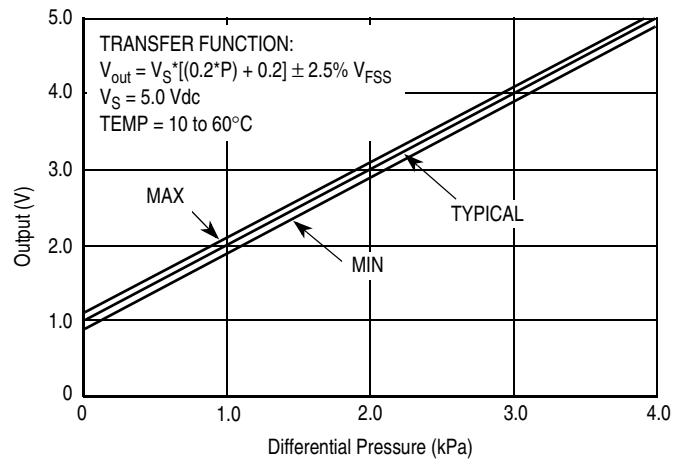
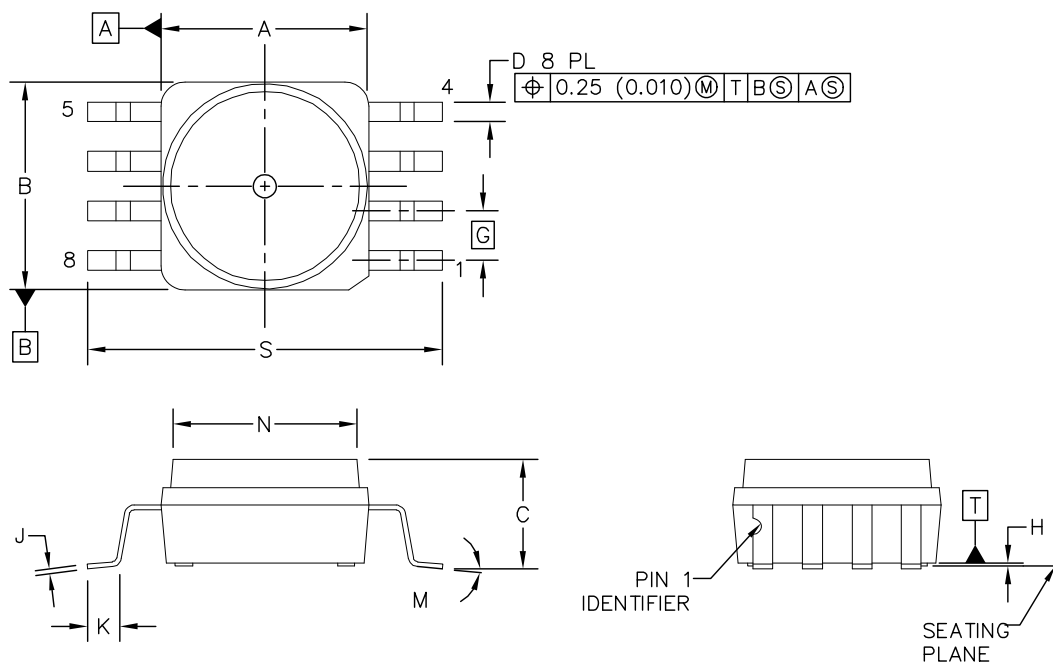


Figure 6. Output vs. pressure differential at $\pm 2.5\% V_{FSS}$ (with autozero, [Table 3](#), note 5)

4.3 Package Dimensions

This drawing is located at http://cache.freescale.com/files/shared/doc/package_info/98ASB17756C.pdf.



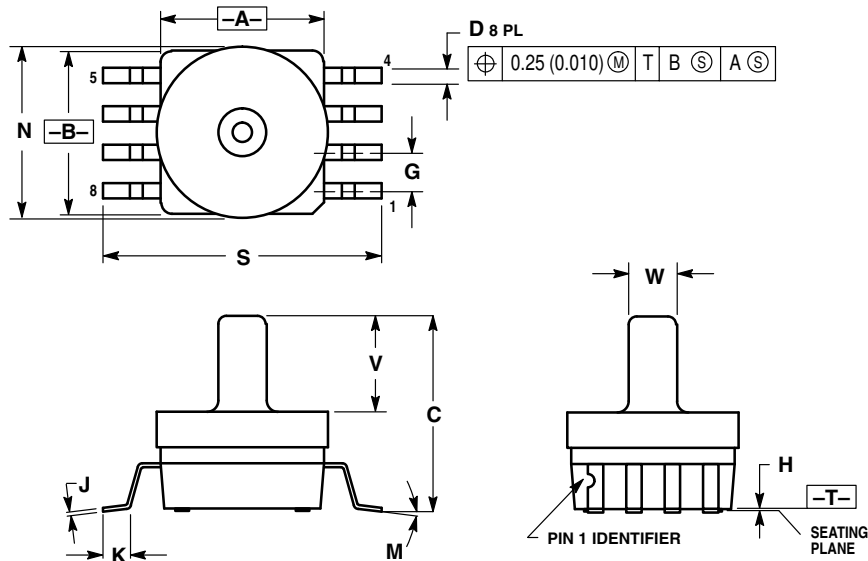
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION "A" AND "B" DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

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TITLE: 8 LD SENSOR SOP		DOCUMENT NO: 98ASB17756C	REV: A
		STANDARD: NON-JEDEC	
			10 JAN 2013

Case 98ASB17756C, small outline package, surface mount

This drawing is located at http://cache.freescale.com/files/shared/doc/package_info/98ASB17757C.pdf.

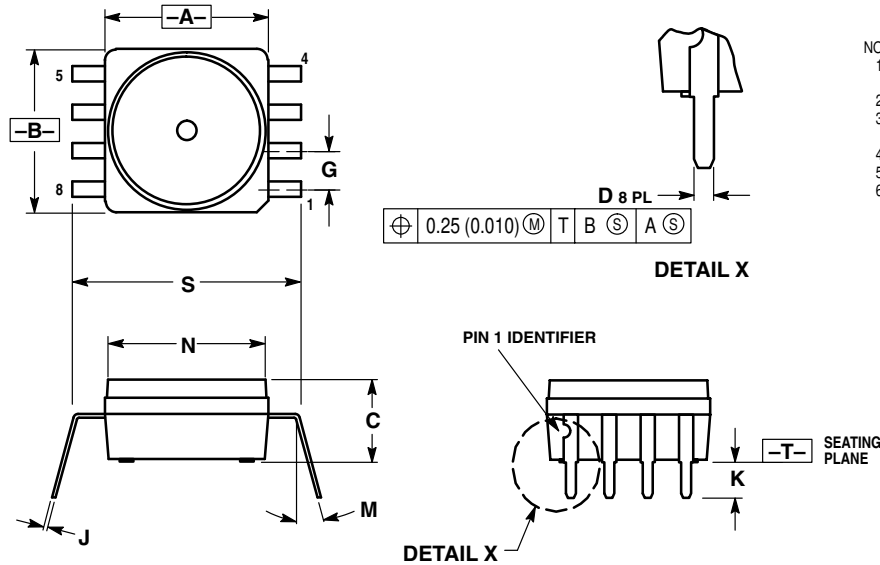


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
 5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.500	0.520	12.70	13.21
D	0.038	0.042	0.96	1.07
G	0.100 BSC		2.54 BSC	
H	0.002	0.010	0.05	0.25
J	0.009	0.011	0.23	0.28
K	0.061	0.071	1.55	1.80
M	0°	7°	0°	7°
N	0.444	0.448	11.28	11.38
S	0.709	0.725	18.01	18.41
V	0.245	0.255	6.22	6.48
W	0.115	0.125	2.92	3.17

Case 98ASB17757C, small outline package, through-hole

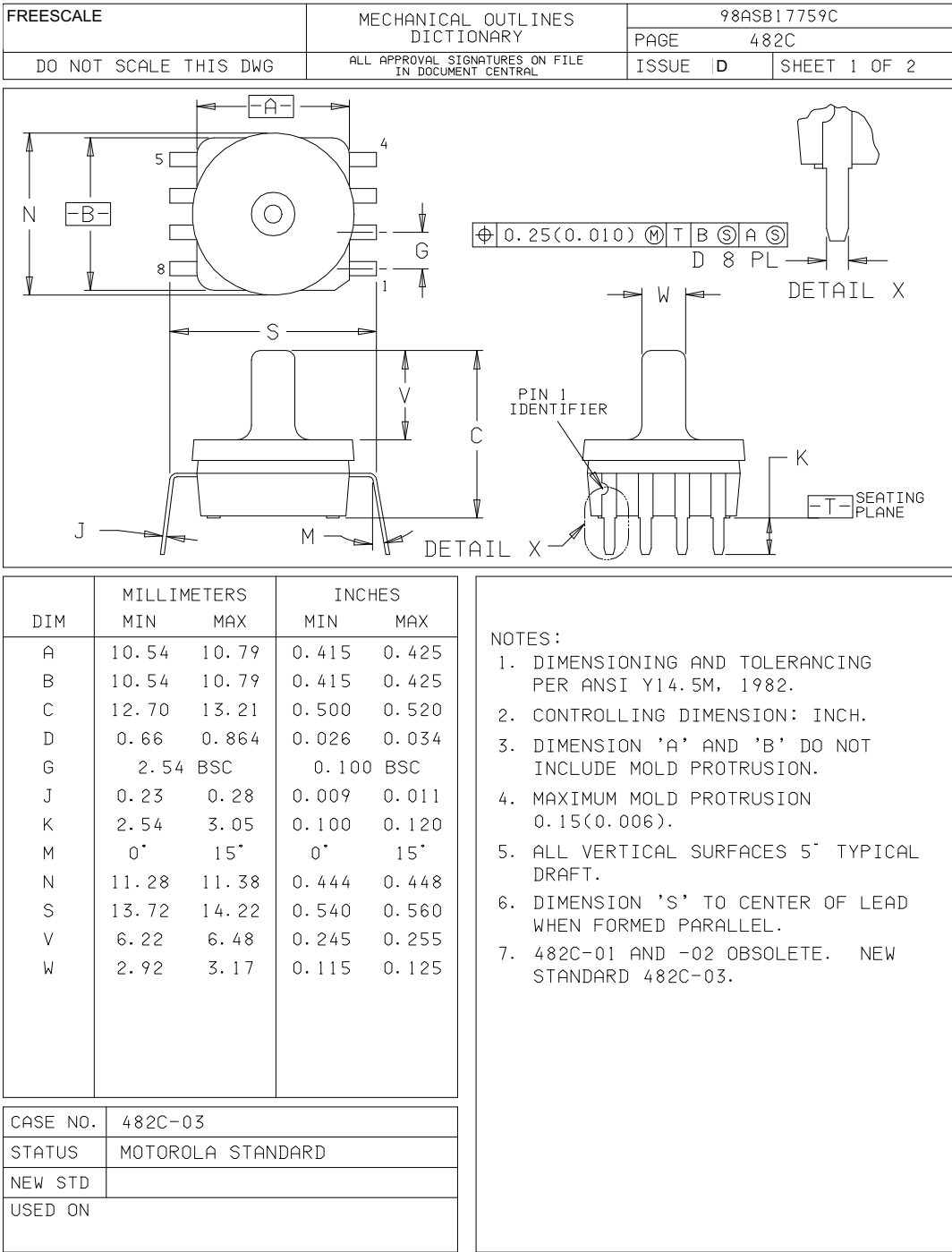
This drawing is located at http://cache.freescale.com/files/shared/doc/package_info/98ASB17758C.pdf.



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
 5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
 6. DIMENSION S TO CENTER OF LEAD WHEN FORMED PARALLEL.

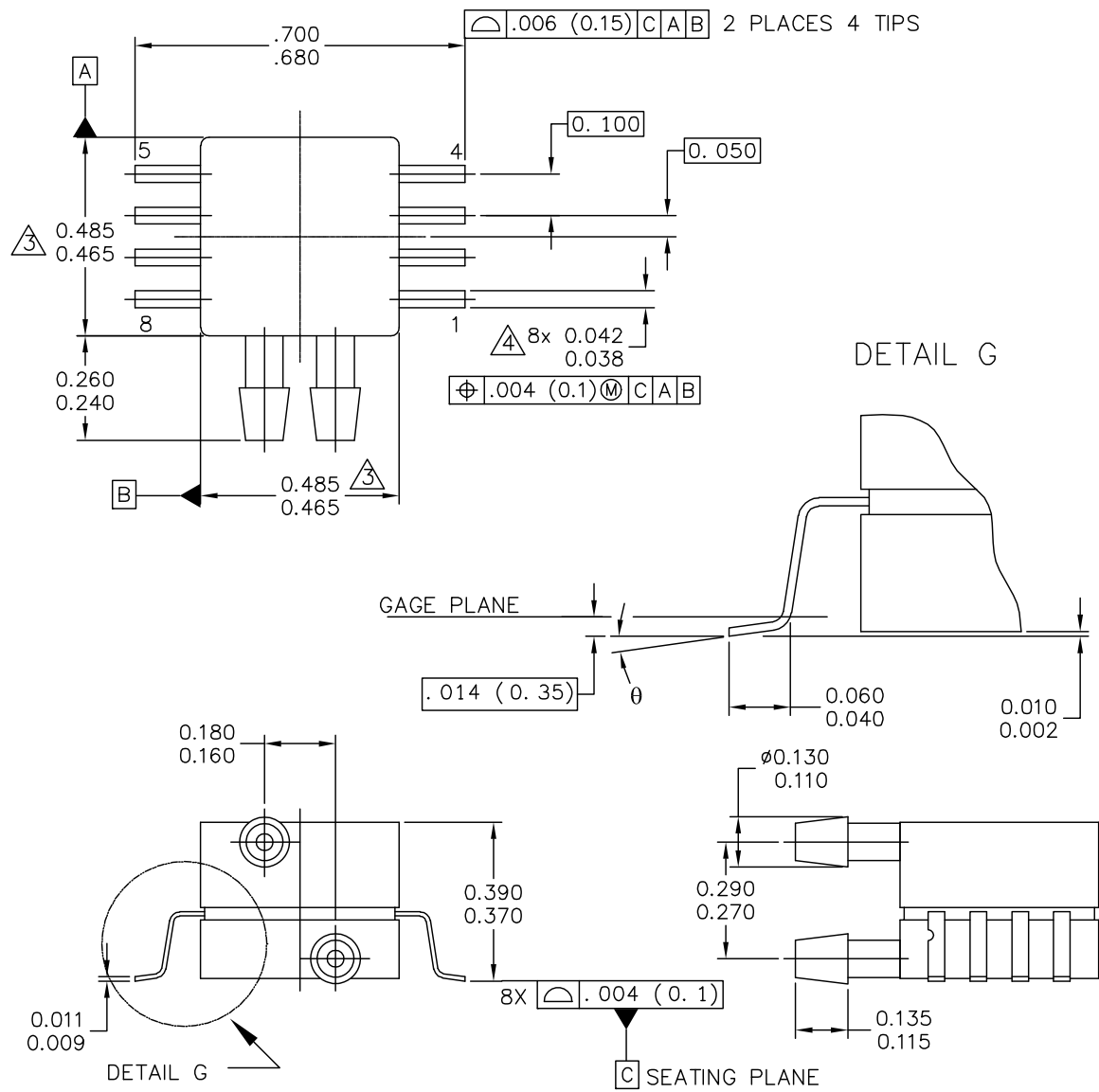
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.210	0.220	5.33	5.59
D	0.026	0.034	0.66	0.864
G	0.100 BSC		2.54 BSC	
J	0.009	0.011	0.23	0.28
K	0.100	0.120	2.54	3.05
M	0°	15°	0°	15°
N	0.405	0.415	10.29	10.54
S	0.540	0.560	13.72	14.22

Case 98ASB17758C, small outline package, through-hole



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Case 98ASB17759C, small outline package, through-hole



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	CASE NUMBER: 1351-01	27 JUL 2005
	STANDARD: NON-JEDEC	

Case 98ASA99255D, small outline package, surface mount

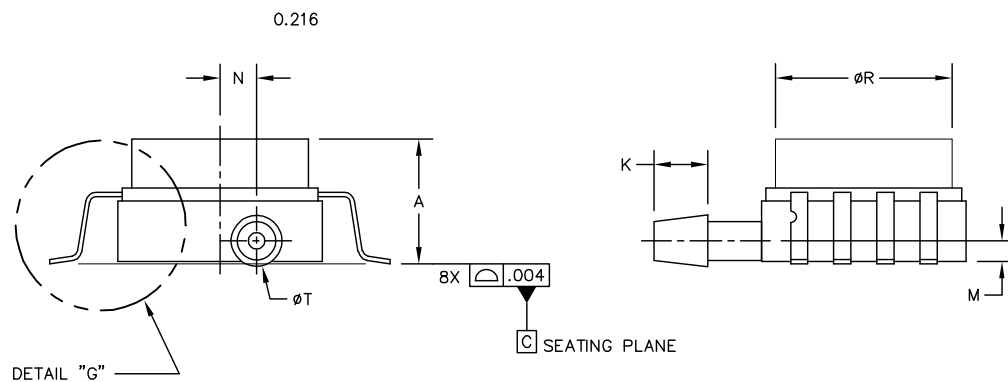
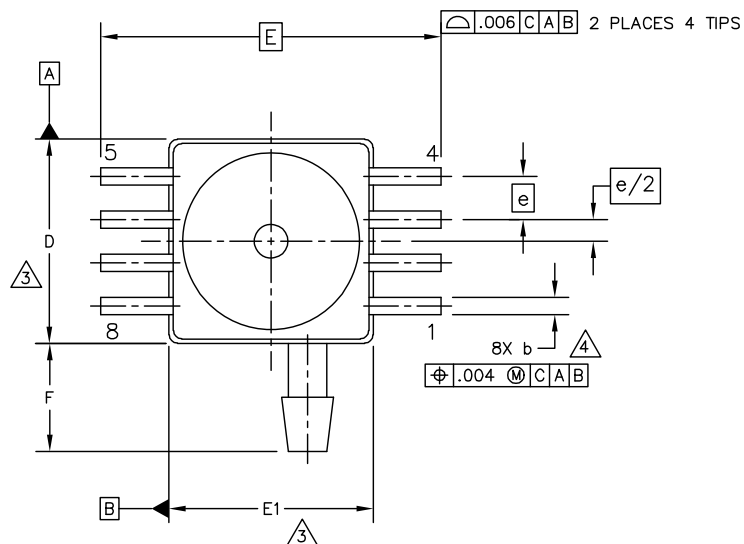
NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.
4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

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TITLE: 8 LD SNSR, DUAL PORT	DOCUMENT NO: 98ASA99255D	REV: A
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	STANDARD: NON-JEDEC	

PAGE 2 OF 2

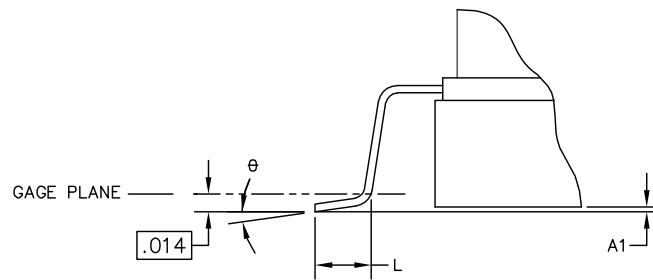
Case 98ASA99255D, small outline package, surface mount



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TITLE: 8 LD SOP, GVP		DOCUMENT NO: 98ASA99302D		REV: C	
		CASE NUMBER: 1368-01		18 DEC 2008	
		STANDARD: NON-JEDEC			

PAGE 1 OF 3

Case 98ASA99302D, small outline package, surface mount



DETAIL "G"

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TITLE: 8 LD SOP, GVP		DOCUMENT NO: 98ASA99302D		REV: C
		CASE NUMBER: 1368-01		18 DEC 2008
		STANDARD: NON-JEDEC		

PAGE 2 OF 3

Case 98ASA99302D, small outline package, surface mount

NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

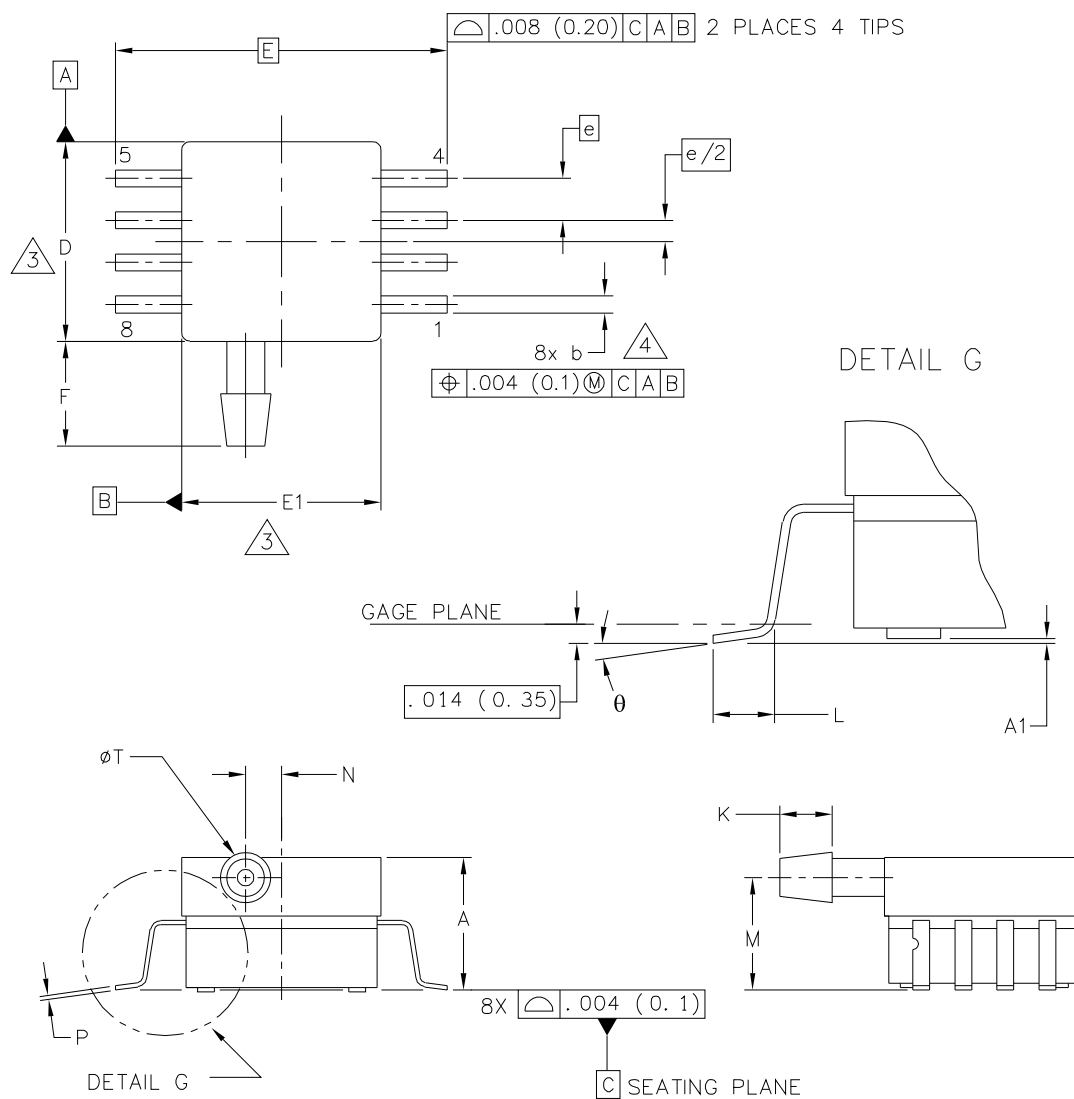
3. THIS DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.

4. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
PROTRUSION SHALL BE .008 MAXIMUM.

DIM	INCHES		MILLIMETERS		DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.280	.300	7.11	7.62	R	.405	.415	10.28	10.54
A1	.002	.010	0.05	0.25	Ø	0"	7"	0"	7"
b	.038	.042	0.96	1.07	—	---	---	---	---
D	.465	.485	11.81	12.32	—	---	---	---	---
E	.690 BSC		17.52 BSC		—	---	---	---	---
E1	.465	.485	11.81	12.32	—	---	---	---	---
e	.100 BSC		2.54 BSC		—	---	---	---	---
F	.240	.260	6.10	6.60	—	---	---	---	---
K	.115	.135	2.92	3.43	—	---	---	---	---
L	.040	.060	1.02	1.52	—	---	---	---	---
M	.035	.055	0.89	1.39	—	---	---	---	---
N	.075	.095	1.90	2.41	—	---	---	---	---
P	.009	.011	0.23	0.28	—	---	---	---	---
T	.110	.130	2.79	3.30	—	---	---	---	---
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TITLE: 8 LD SOP, GVP					DOCUMENT NO: 98ASA99302D				REV: C
					CASE NUMBER: 1368-01				18 DEC 2008
					STANDARD: NON-JEDEC				

PAGE 3 OF 3

Case 98ASA99302D, small outline package, surface mount



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TITLE: 8 LD SOP, SIDE PORT		DOCUMENT NO: 98ASA99303D	REV: D	
		CASE NUMBER: 1369-01	13 DEC 2010	
		STANDARD: NON-JEDEC		

PAGE 1 OF 2

Case 98ASA99303D, small outline package

NOTES:

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2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

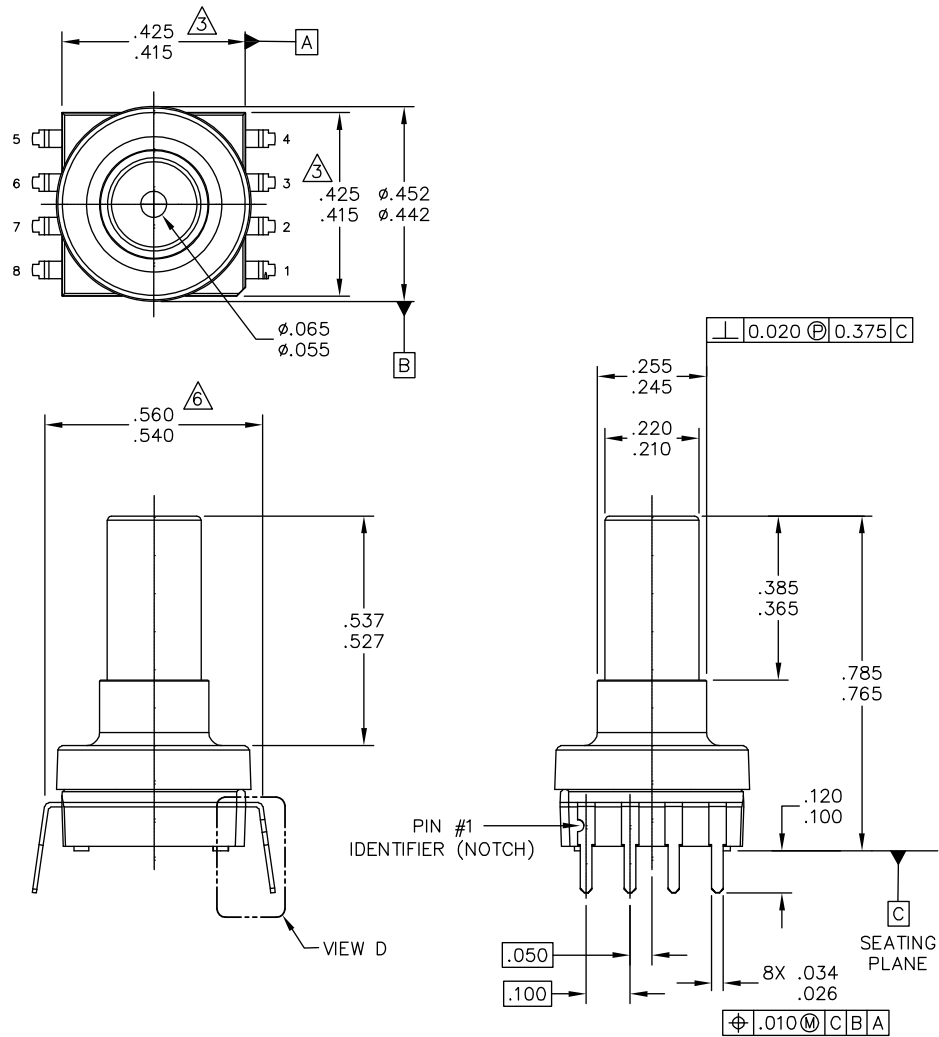
 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 (0.152) PER SIDE.

 DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 (0.203) MAXIMUM.

DIM	INCHES		MILLIMETERS		DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.300	.330	7.62	8.38	Ø	0°	7°	0°	7°
A1	.002	.010	0.05	0.25	—	---	---	---	---
b	.038	.042	0.96	1.07	—	---	---	---	---
D	.465	.485	11.81	12.32	—	---	---	---	---
E	.717 BSC		18.21 BSC		—	---	---	---	---
E1	.465	.485	11.81	12.32	—	---	---	---	---
e	.100 BSC		2.54 BSC		—	---	---	---	---
F	.245	.255	6.22	6.47	—	---	---	---	---
K	.120	.130	3.05	3.30	—	---	---	---	---
L	.061	.071	1.55	1.80	—	---	---	---	---
M	.270	.290	6.86	7.36	—	---	---	---	---
N	.080	.090	2.03	2.28	—	---	---	---	---
P	.009	.011	0.23	0.28	—	---	---	---	---
T	.115	.125	2.92	3.17	—	---	---	---	---
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TITLE: 8 LD SOP, SIDE PORT					DOCUMENT NO: 98ASA99303D				REV: D
					CASE NUMBER: 1369-01				13 DEC 2010
					STANDARD: NON-JEDEC				

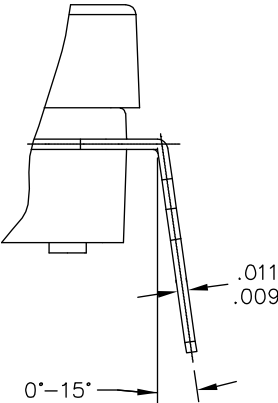
PAGE 2 OF 2

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TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA10611D		REV: D
	CASE NUMBER: 1560-03		25 FEB 2009
	STANDARD: NON-JEDEC		

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VIEW D

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TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH		DOCUMENT NO: 98ASA10611D		REV: D	
		CASE NUMBER: 1560-03		25 FEB 2009	
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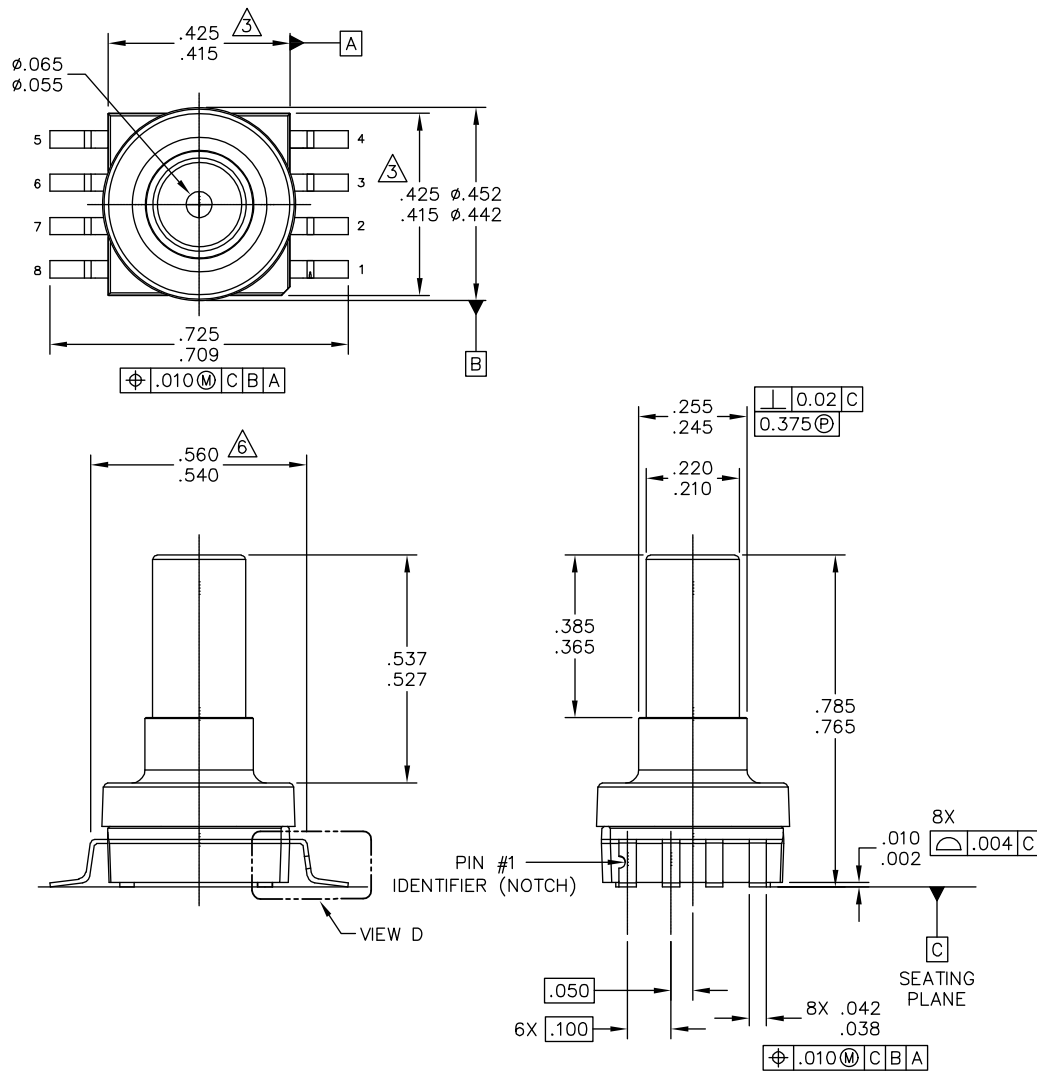
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NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M – 1994.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION IS .006.
- 5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
- 6. DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.

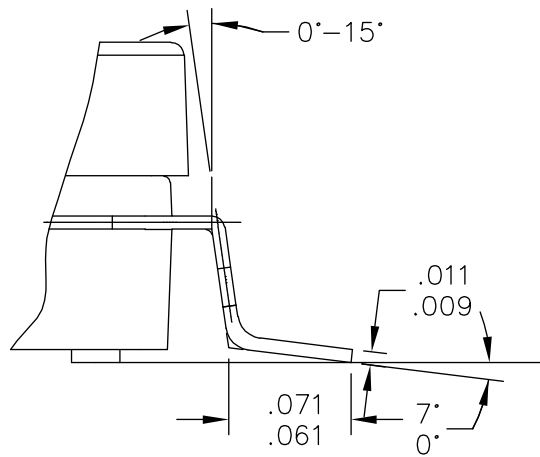
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TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH		DOCUMENT NO: 98ASA10611D		REV: D	
		CASE NUMBER: 1560-03		25 FEB 2009	
		STANDARD: NON-JEDEC			

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TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA10686D		REV: B
	CASE NUMBER: 1735-02		19 FEB 2009
	STANDARD: NON-JEDEC		

Case 98ASA10686D, small outline package



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TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA10686D		REV: B	
	CASE NUMBER: 1735-02		19 FEB 2009	
	STANDARD: NON-JEDEC			

PAGE 2 OF 3

Case 98ASA10686D, small outline package

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M – 1994.
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- 3. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION IS .006.
- 5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
- 6. DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.

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TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH		DOCUMENT NO: 98ASA10686D	REV: B
		CASE NUMBER: 1735-02	19 FEB 2009
		STANDARD: NON-JEDEC	

Case 98ASA10686D, small outline package

5 Revision History

Table 5. Revision history

Revision number	Revision date	Description
12.1	05/2015	• Updated format. • Table 3: Updated Full-scale span Typ value, was 4.0 to 3.92. Updated Linearity definition in note 4. • Updated package drawings with current versions.



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